

AIAA SPACE 2007



# Avionics, Surface and Mission Operations Logistics Session

Exploration Technology Development Program's

## Radiation Hardened Electronics for Space Environments (RHESE)

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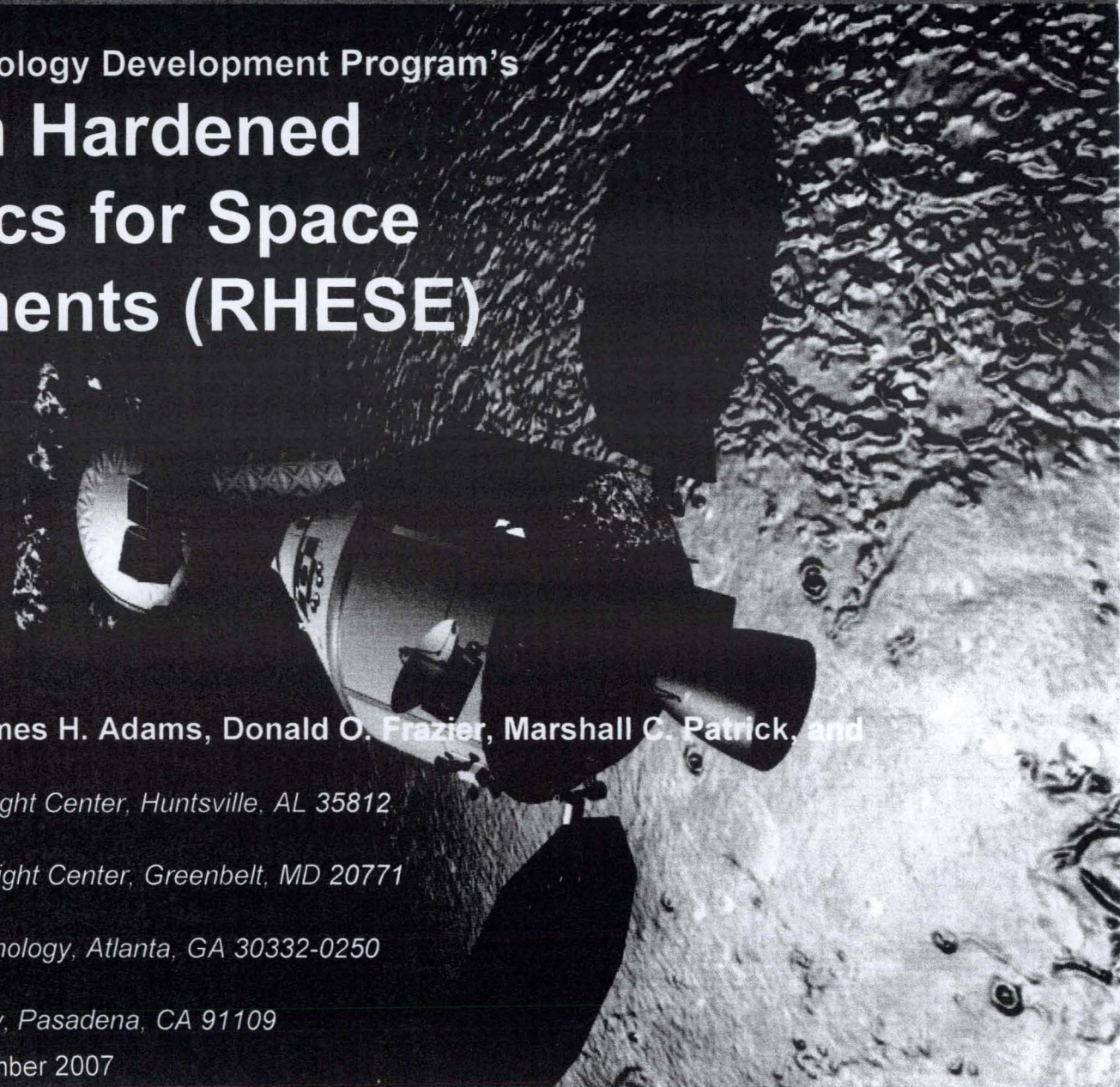
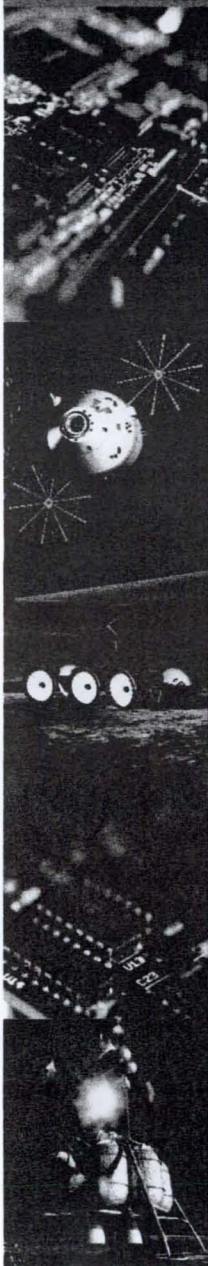
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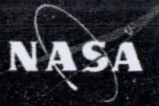
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# Vision for Space Exploration



- **The Vision for Space Exploration (VSE) directs NASA to pursue a long-term human and robotic program to explore the solar system.**
- **The VSE is based on the following goals:**
  - Return the shuttle to flight (following the Columbia accident) and complete the International Space Station by 2010.
  - Develop a Crew Exploration Vehicle, test by 2008, first manned mission no later than 2014.
  - Return to the Moon as early as 2015 and no later than 2020.
    - Gain experience and knowledge for human missions to Mars.
    - Increase the use of robotic exploration to maximize our understanding of the solar system.

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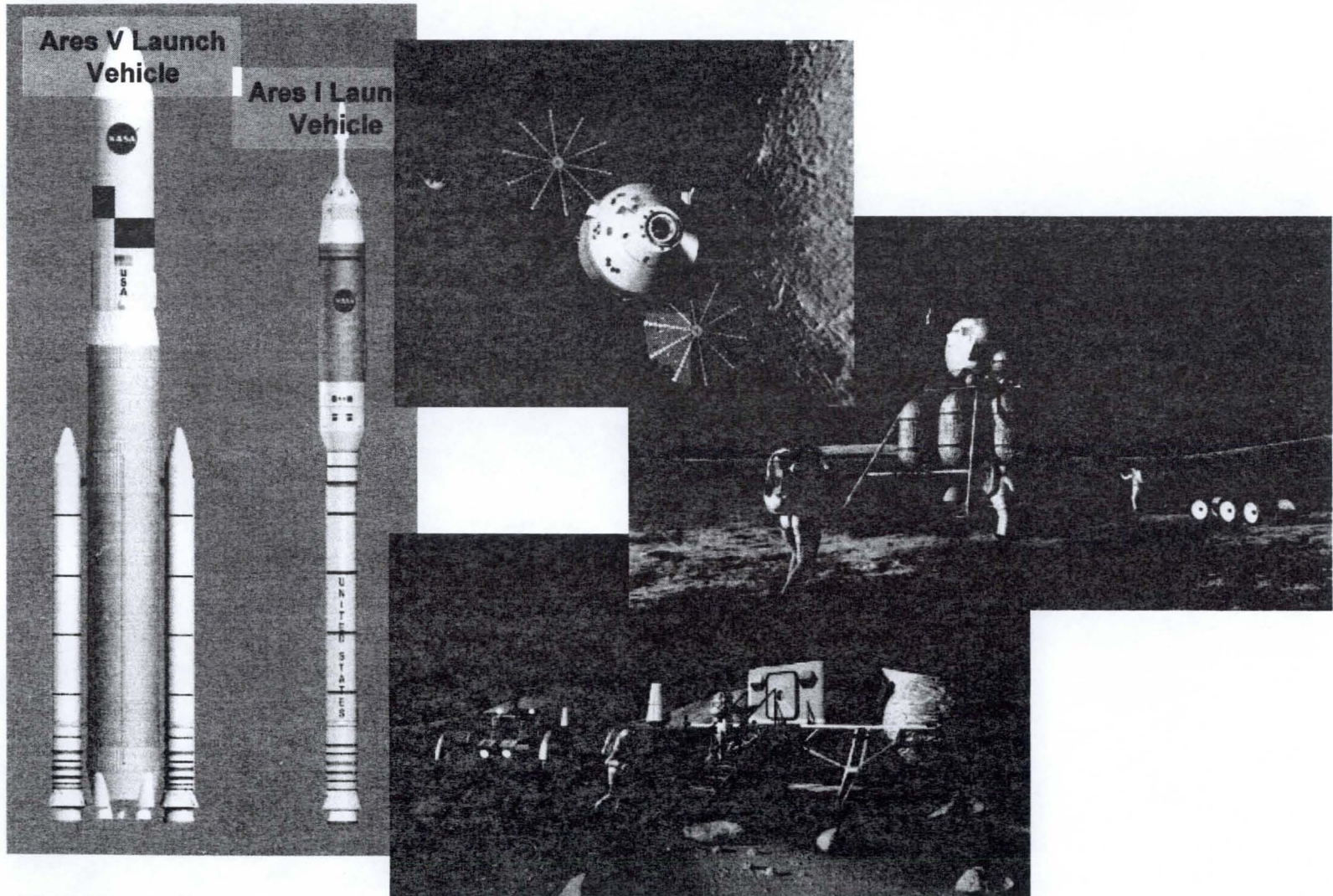


National Aeronautics and  
Space Administration

## The Vision for Space Exploration

February 2004

- **The Constellation Program consists of multiple projects, jointly being developed to fulfill the goals of the VSE.**

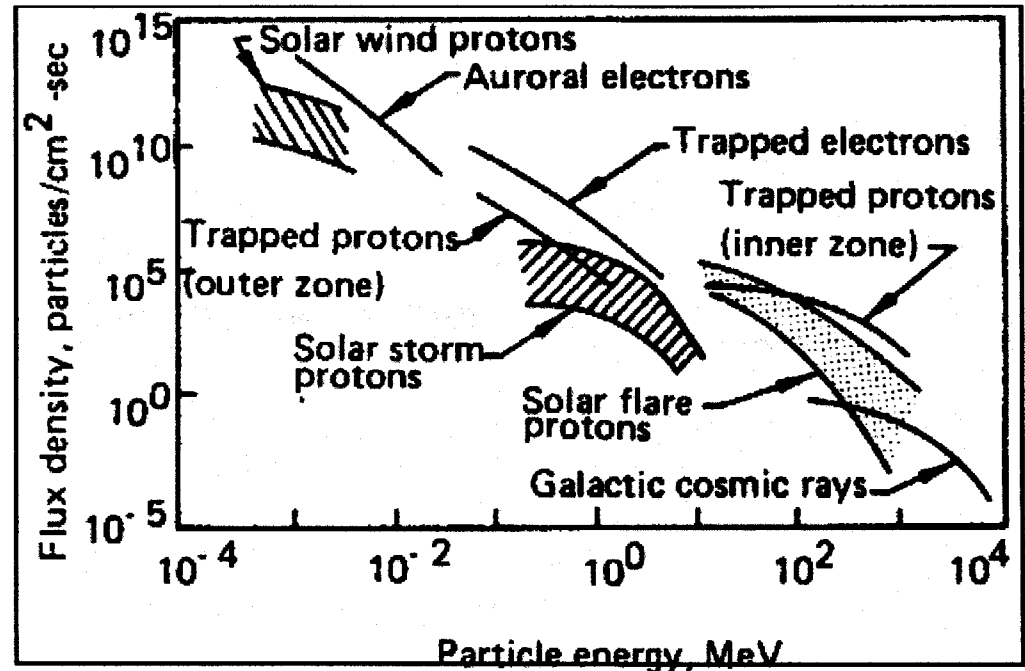


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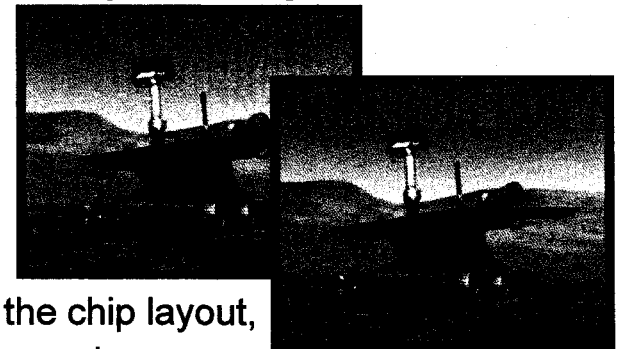
- **Space Radiation affects all spacecraft.**

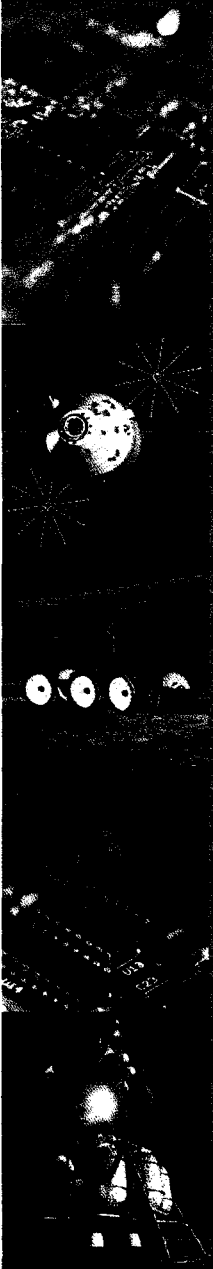
- Spacecraft electronics have a long history of power resets, safing, and system failures due to:

- Long duration exposures,
- Unpredictable solar proton activity,
- Ambient galactic cosmic ray environment.




- **Multiple approaches may be employed (independently or in combination) to protect electronic systems in the radiation environment:**
  - Shielding,
  - Mission Design (radiation avoidance),
  - Radiation Hardening by Architecture,
    - Commercial parts in redundant and duplicative configurations (Triple Module Redundancy),
    - Increases overhead in voting logic, power consumption, flight mass
    - Multiple levels of redundancy implemented for rad-damage risk mitigation:
      - Component level
      - Board level
      - Subsystem level
      - Spacecraft level
  - Radiation Hardening by Design,
    - TMR strategies within the chip layout,
    - designing dopant wells and isolation trenches into the chip layout,
    - implementing error detecting and correction circuits, and
    - device spacing and decoupling.
  - Radiation Hardening by Process,
    - Employ specific materials, processing techniques,
    - Usually performed on dedicated rad-hard foundry fabrication lines.



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- **NASA spacecraft developers have defined a Radiation Hardness Assurance (RHA) methodology process\*.**
  - **In general, the process may be described by the following steps:**
    - 1) define the radiation hazard,
    - 2) evaluate the hazard,
    - 3) define the requirements to be met by the spacecraft's electronics,
    - 4) evaluate the electronics to be used,
    - 5) engineer processes to mitigate hazard damage, and
    - 6) iterate on the methodology, if and when necessary.
  - **To promote the successful implementation of RHA for Constellation (and other NASA) missions, the RHESE project aims to deliver products that assist in *mitigating the hazard damage*.**

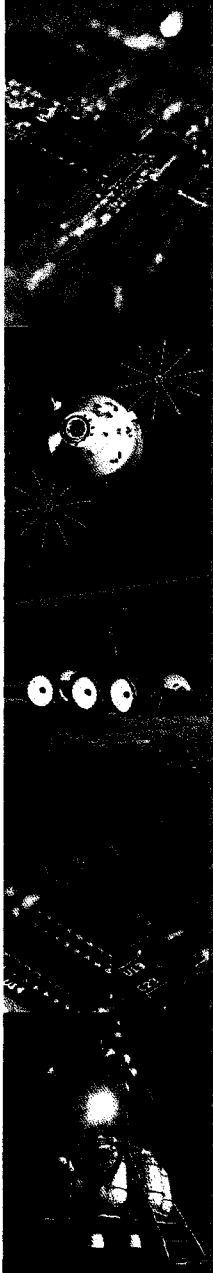
\*LaBel, K. A., Johnson, A. H., Barth, J. L., Reed, R. A., and Barnes, C. E., "Emerging Radiation Hardness Assurance(RHA) Issues: A NASA Approach for Space Flight Programs," *IEEE Transactions on Nuclear Science*, Vol. 45, No. 6, Dec. 1998, pp. 2727-2736.



The **Radiation Hardened Electronics for Space Environments (RHESE)** project expands the current state-of-the-art in radiation-hardened electronics to develop high performance devices robust enough to withstand the demanding radiation and thermal conditions encountered within the space and lunar environments.

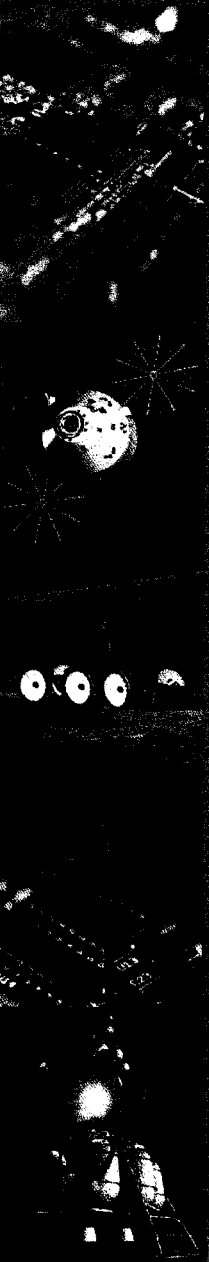
**The specific goals of the RHESE project are to foster technology development efforts in radiation-hardened electronics possessing these associated capabilities:**

- improved total ionization dose (TID) tolerance,
- reduced single event upset rates,
- increased threshold for single event latch-up,
- increased sustained processor performance,
- increased processor efficiency,
- increased speed of dynamic reconfigurability,
- reduced operating temperature range's lower bound,
- increased the available levels of redundancy and reconfigurability, and
- increased the reliability and accuracy of radiation effects modeling.

- 
- **RHESE is a “requirements-pull” technology development effort.**
  - **RHESE is a “cross-cutting” technology, serving a broad base of multiple project customers within Constellation.**
    - Every project requiring...
      - operation in an extreme space environment,
      - avionics, processors, automation, communications, etc.
    - ...should include RHESE in its implementation trade space.
  - **RHESE’s products are developed in response to the needs and requirements of multiple Constellation program elements, including:**
    - Ares V Crew Launch Vehicle,
    - Orion Crew Exploration Vehicle’s lunar capability,
    - Lunar Lander,
    - Lunar Outpost,
    - Surface Systems,
    - Extra Vehicular Activity (EVA) elements,
    - Future applications to Mars exploration architecture elements.
  - **Constellation Program requirements for avionics and electronics continue to evolve and become more defined.**
  - **RHESE will develop products per derived requirements based on the Constellation Architecture’s Level I and Level II requirements defined to date.**

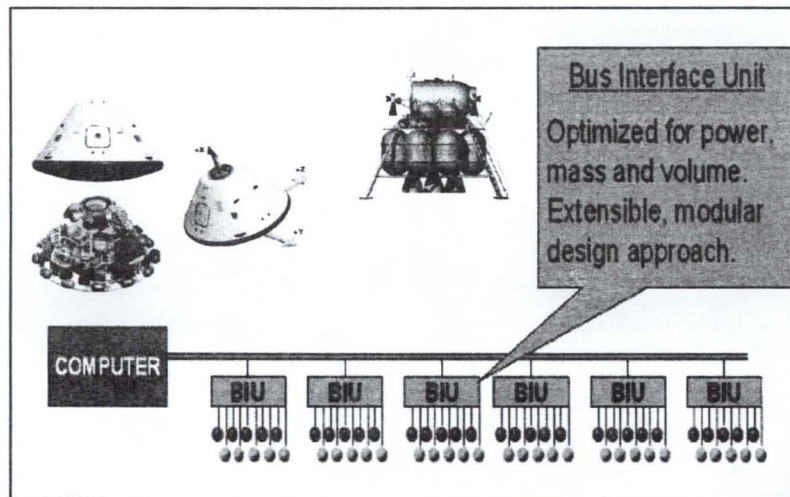


- **Specifically, the RHESE tasks are:**
  - Model of Radiation Effects on Electronics (MREE),
  - Single Event Effects (SEE) Immune Reconfigurable Field Programmable Gate Array (FPGA) (SIRF),
  - Radiation Hardened High Performance Processors (HPP),
  - Reconfigurable Computing (RC),
  - Silicon-Germanium (SiGe) Integrated Electronics for Extreme Environments.

- 
- **The Main Objective**
    - A computational tool to estimate radiation effects in space in support of spacecraft design
      - Total dose
      - Single Event Effects
  - **Secondary Objectives**
    - To provide a detailed description of the radiation environment in support of radiation health and instrument design
      - In deep space
      - Inside the magnetosphere
      - Behind shielding



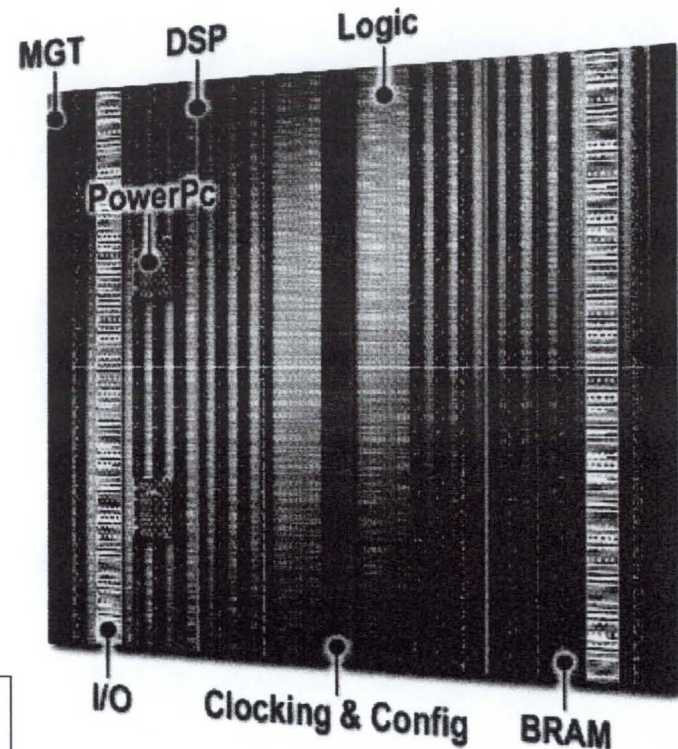
- **Reconfigurable gate arrays form the basis of many adaptable, scaleable, computing engines**
  - Add flexibility, capability and robustness to surface and flight systems



# SIRF Architecture Based on Commercial Devices



- **5th generation Virtex™ device**
  - 90 nm process
  - 11 metal layers
  - Up to 8M gates
- **Columnar Architecture enables resource “dial-in” of**
  - Logic
  - Block RAM
  - I/O
  - DSP Slices
  - PowerPC Cores

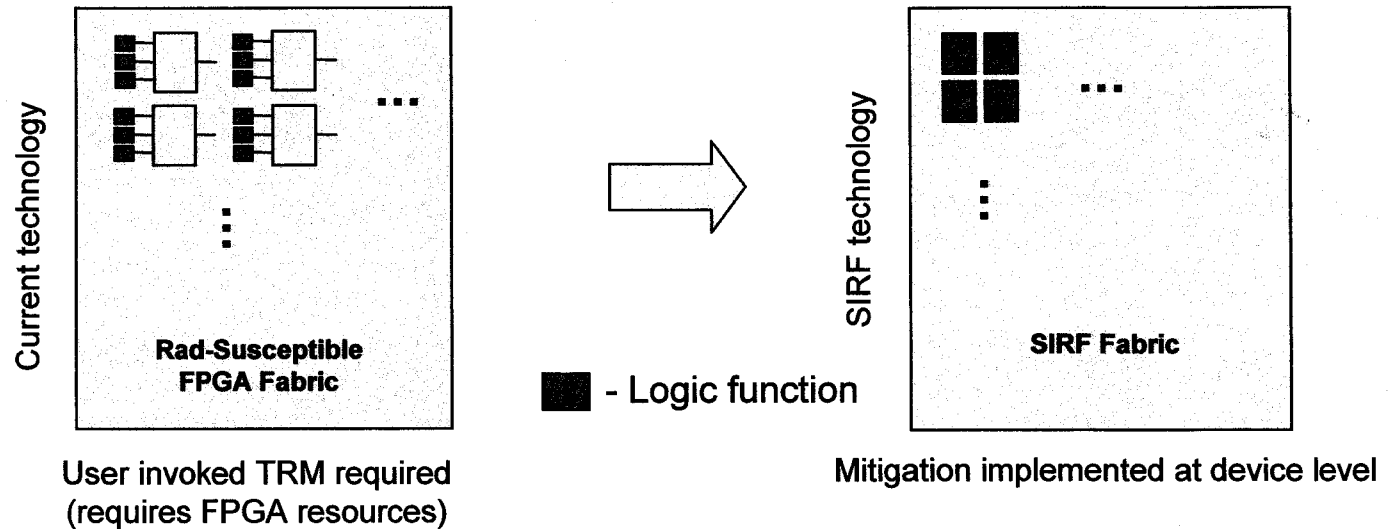


Fabrication process and device architecture  
yield a high speed, flexible component

# SIRF Objective Radiation-hardened Device



- **Existing reconfigurable FPGAs are very susceptible to radiation-induced single event effects**
  - Significant FPGA resources are currently required to mitigate radiation-induced single event effects

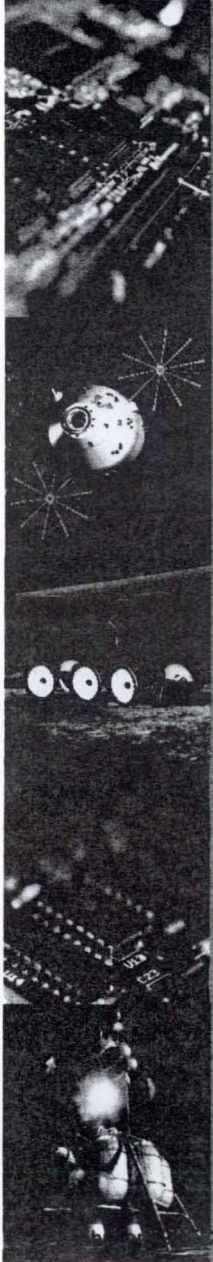


Objectives: Eliminate need for user-invoked TMR. Bring a state-of-the-art radiation hardened reconfigurable FPGA to the space electronics market by ~2010.



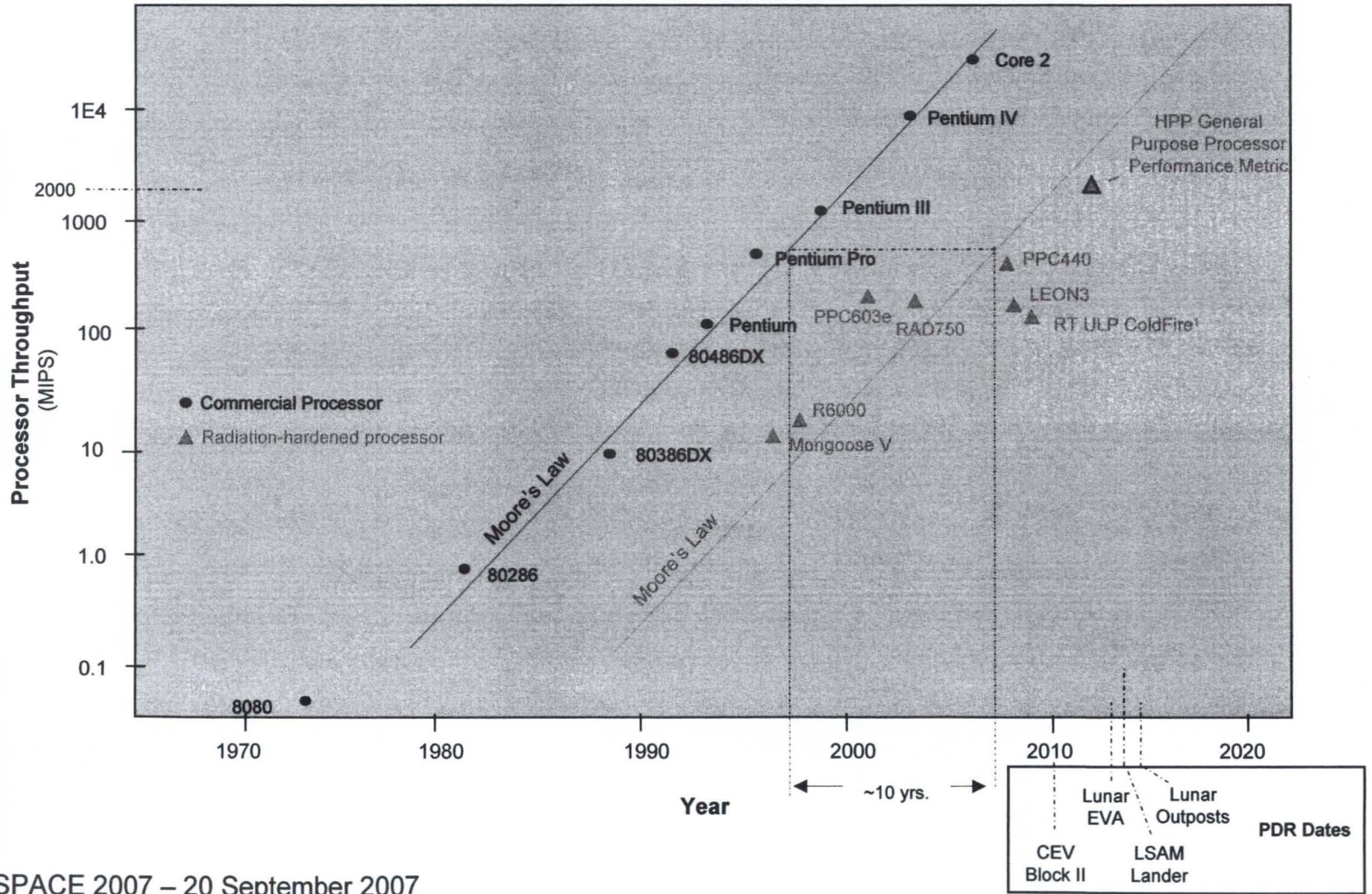
# HPP Technical Approach

## Multi-generation Performance Lag



Radiation-hardened processors lag commercial devices by several technology generations (approx. 10 years)

- RHESE High performance Processor project full-success metric for general purpose processors conservatively keeps pace with historical trend (~Moore's Law)

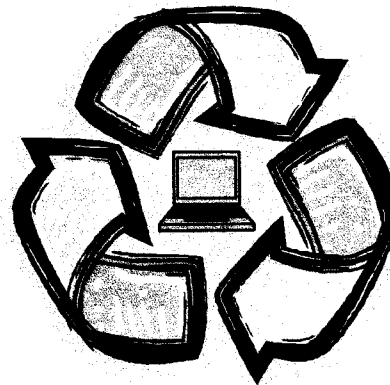


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# Reconfigurable Computing Subproject

- Subproject Objectives
- **Provide reconfigurable computing capabilities as a preferred alternative to conventional forms**
  - Processor Modularity
  - Interface Modularity
    - Reduction of Flight Spares
    - Accommodation for Circuit Life Limitations
    - Resources where needed, as needed
- **Supplement other efforts to mitigate environmental impacts by providing the capability to detect and work around malfunctioning circuitry**
  - Fault Tolerance
  - Fault Detection, Isolation, and Mitigation
- **Generally: capitalize on the unique capabilities of RC to adapt in target systems for changing requirements, performance and environmental parameters**



# RC Technical Justification

## Reconfigurable Computing Subproject

- **Flight-Qualified, Multi-String Redundant Hardware is Expensive**
  - Development, Integration, IV&V, and Flight Qualification
  - Space and Weight
  - Power Consumption and Cooling
- **Custom Design of Computing Resources for Every New Flight System or Subsystem is Unnecessary and Wasteful**
- **Requirements for Flexibility are Increasing and Make Sense**
  - Reconfigurable (Flexible) and Modular Capabilities
  - For Dissimilar Spares, and Incremental Changeover to New Technology:  
Capacity to use one system to back up any number of others
  - General Reusability
- **Current Options for Harsh/Flight Environment Systems are Limited**
  - Custom Hardware, Firmware, and Software
  - Dedicated and Inflexible
  - Often Proprietary: Collaboration Inhibited
- **Modular Spares == Fewer Flight Spares**

**The Moon: A Classic Extreme Environment!****Extreme Temperature Ranges:**

- +120C to -180C (300C T swings!)
- 28 day cycles
- -230C in shadowed polar craters

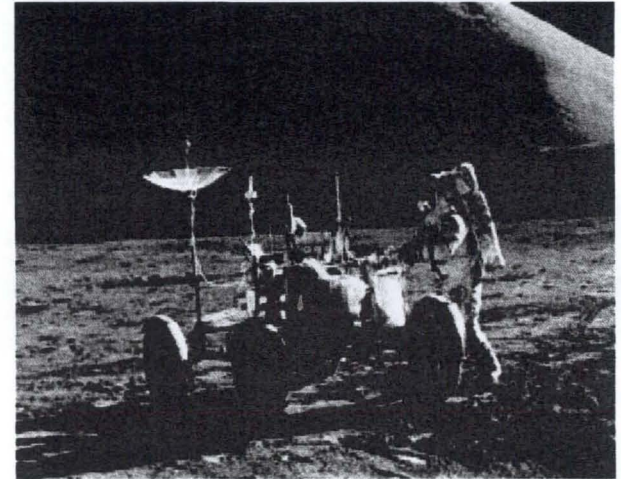
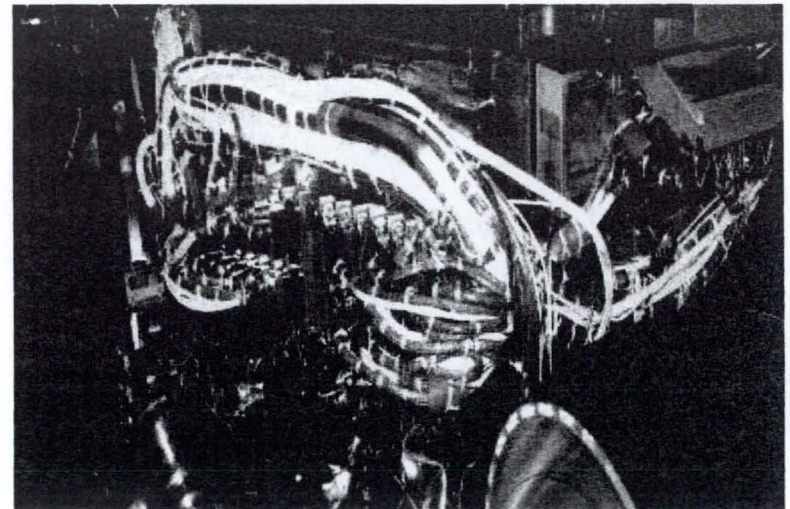
**Radiation:**

- 100 krad over 10 years
- single event effects (SEE)
- solar events

**Many Different Circuit Needs:**

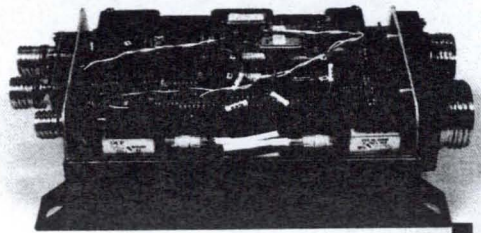
- digital building blocks
- analog building blocks
- data conversion (ADC/DAC)
- RF communications
- actuation and control
- sensors / sensor interfaces

➔ Highly Mixed-Signal Flavor

**Current Rovers / Robotics****Requires “Warm Box”**



# SiGe-Based Remote Electronics Unit (REU)

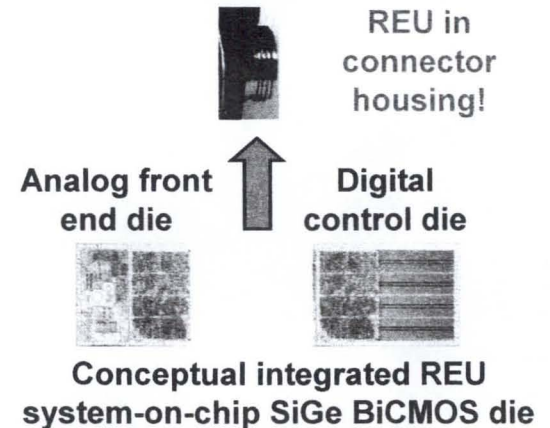
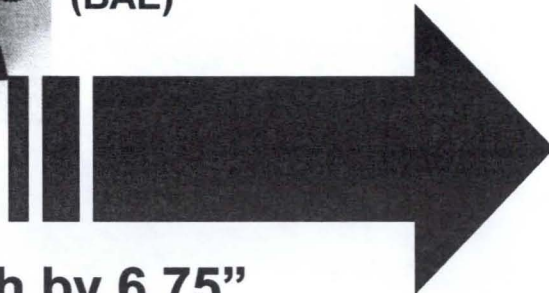


The X-33 Remote Health Monitoring Node, circa 1998 (BAE)

Our Project End Game:  
The SiGe ETDP Remote Electronics Unit, circa 2009

## Specifications

- 5" wide by 3" high by 6.75" long = 101 cubic inches
- 11 kg weight
- 17.2 Watts power dissipation
- -55°C to +125°C



## Our Goals

- 1.5" high by 1.5" wide by 0.5" long = 1.1 cubic inches
- < 1 kg
- < 1-2 Watts
- -180°C to +125°C, rad tolerant!



Supports MANY Sensor Types:

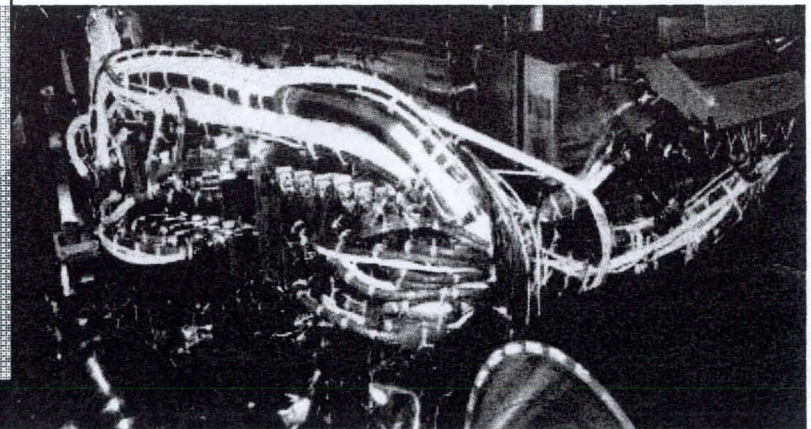
Temperature, Strain, Pressure, Acceleration, Vibration, Heat Flux, Position, etc.

Use This REU as a Remote Vehicle Health Monitoring Node

# RHESE Summary



- All RHESE tasks are “requirements-pulled” by **specific CARD requirements, LAT technology needs, and surface systems’ defined environments.**
- An application-dependent trade space is defined by:
  - Radiation Hardening by Architecture using COTS processors, and
  - Radiation Hardening By Design using Rad-Hard processors.
  - Considerations include performance requirements, power efficiency, design complexity, radiation
- Radiation and low temperature environments currently drive spacecraft system architectures.
  - **Centralized systems** to keep electronics warm are costly, weighty and use excessive cable lengths.
  - Mitigation can be achieved by active **SiGe electronics.**



# RHESE Summary



- Radiation Environmental Modeling is crucial **to proper predictive modeling and electronic response to the radiation environment.**
  - When compared to on-orbit data, CREME96 has been shown to be inaccurate in predicting the radiation environment.
  - The NEDD bases much of its radiation environment data on CREME96 output.
- Close coordination and partnership with DoD radiation-hardened efforts **will result in leveraged - not duplicated or independently developed - technology capabilities of:**
  - Radiation-hardened, reconfigurable FPGA-based electronics,
  - High Performance Processors (NOT duplication or independent development).

